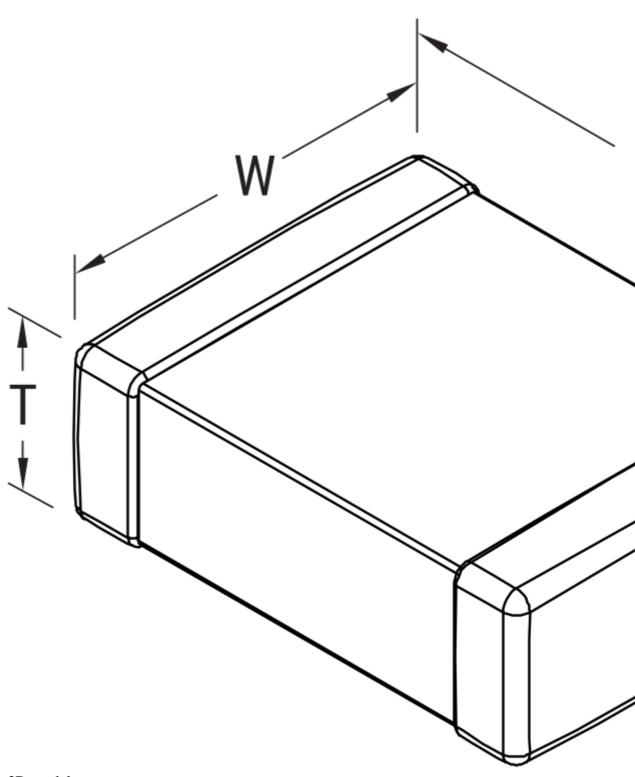
CBR08C889B5GAC

CBR-SMD RF C0G, Ceramic, 8.8~pF, $\pm 0.1~pF$, 50~VDC, C0G, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805~



Click <u>here</u> for the 3D model.

Dimensions

Chip Size 0805

Dimensions

B 0.5mm +/-0.2mm

Packaging Specifications

Packaging T&R, 180mm, Plastic Tape

Packaging Quantity 4000

General Information

Series CBR-SMD RF C0G

Style SMD Chip

Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I

Features Ultra High Q, Low ESR, Class I

RoHS Yes
Termination Tin
Marking No
AEC-Q200 No

Component Weight 10.7 mg

Notes Solder Wave or Solder Reflow.

Shelf Life 78 Weeks

MSL 1

Specifications

Capacitance 8.8 pF
Capacitance Tolerance +/-0.1 pF
Voltage DC 50 VDC
Dielectric Withstanding Voltage 125 VDC
Temperature Range -55/+125°C

Temperature Coefficient C0G

Dissipation Factor 0.174%

Aging Rate 0% Loss/Decade Hour

Insulation Resistance 10 GOhms

Quality Factor 576

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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